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(12) **United States Design Patent**  
**Ignomirello**

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(54) **TRAY**

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(US)

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(52) **U.S. Cl.**  
USPC ..... **D14/439**; D14/432

(58) **Field of Classification Search**  
USPC ..... D14/300–302, 308–313, 314, 348,  
D14/353–355, 432, 439–446, 240;  
361/679.02, 679.31, 679.5, 690, 694,  
361/679.23, 801, 802; 312/332.1, 334.1;  
D13/162; D10/50  
CPC .... B65H 1/00; B65H 1/266; B65H 2402/441;  
B65H 2405/311; B65H 2405/313

See application file for complete search history.

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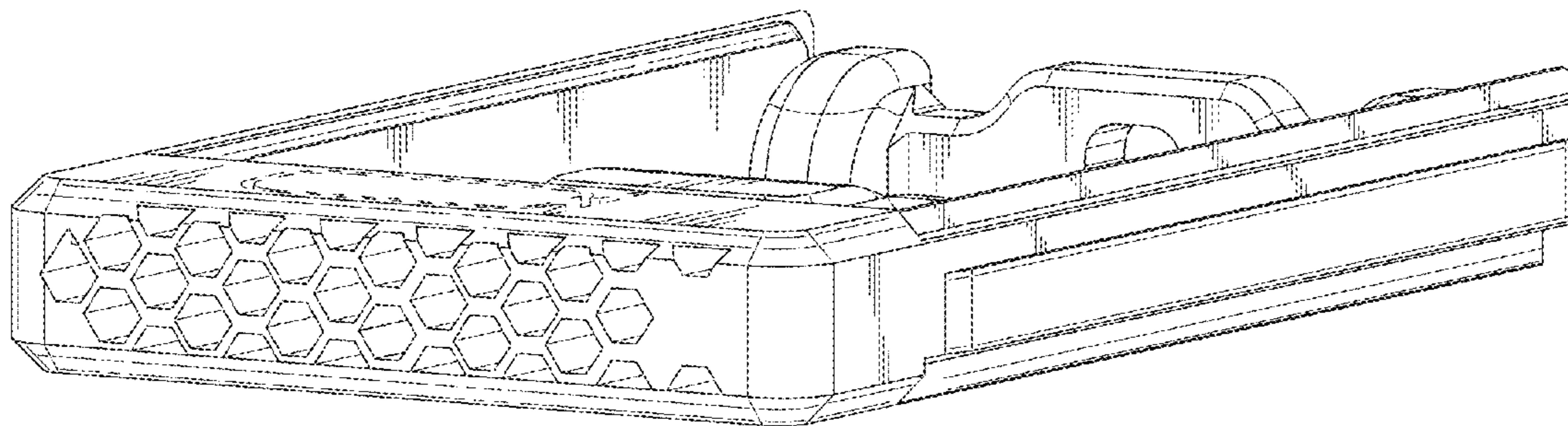
(57) **CLAIM**

The ornamental design for a tray, as shown and described.

**DESCRIPTION**

FIG. 1 is a top and right side perspective view of a tray showing my new design;  
FIG. 2 is a front plan view thereof;  
FIG. 3 is a rear plan view thereof;  
FIG. 4 is a bottom and right side perspective view thereof;  
FIG. 5 is a top and left side perspective view thereof;  
FIG. 6 is a top plan view thereof;  
FIG. 7 is a bottom plan view thereof;  
FIG. 8 is a right side plan view thereof; and,  
FIG. 9 is a left side plan view thereof.

**1 Claim, 9 Drawing Sheets**



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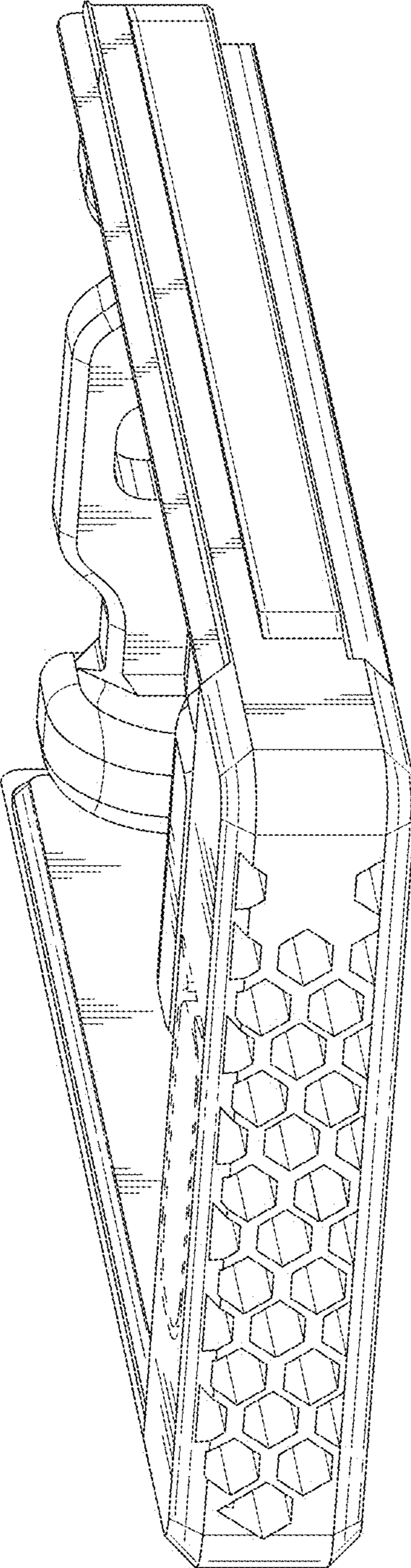


FIG. 1

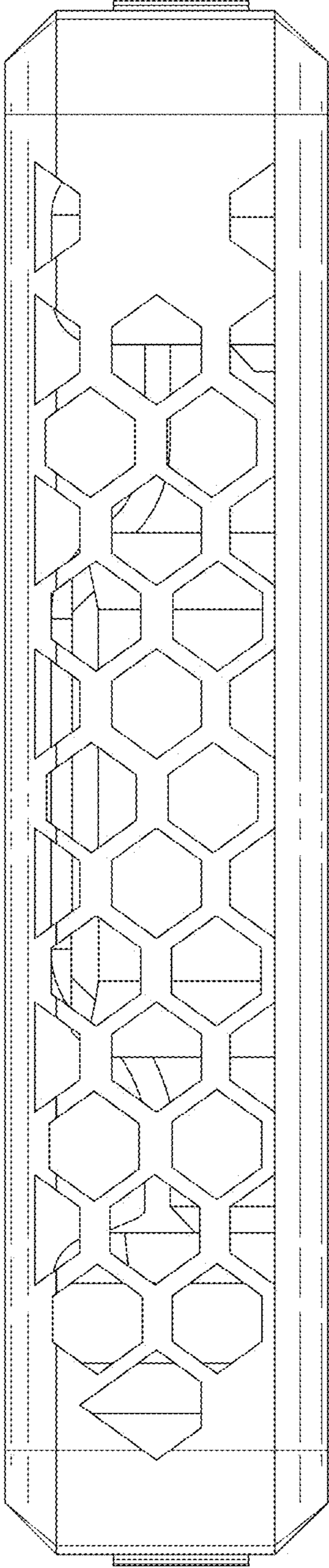


FIG. 2

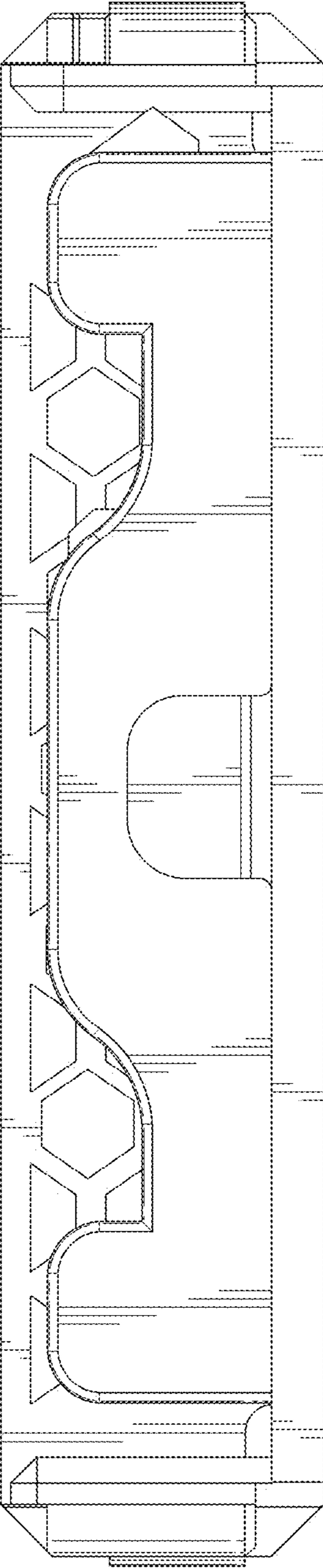


FIG. 3

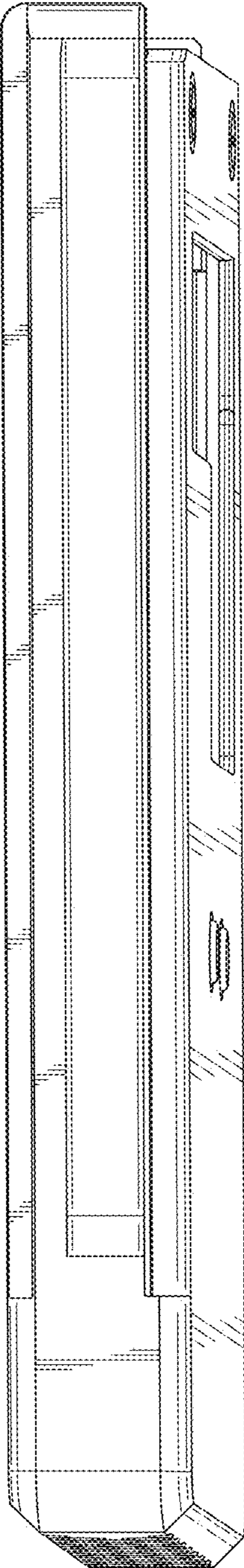


FIG. 4

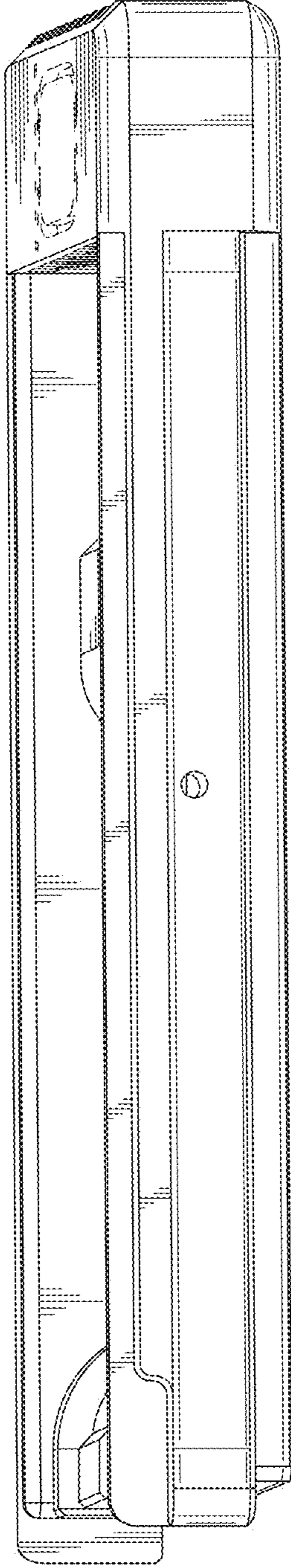


FIG. 5

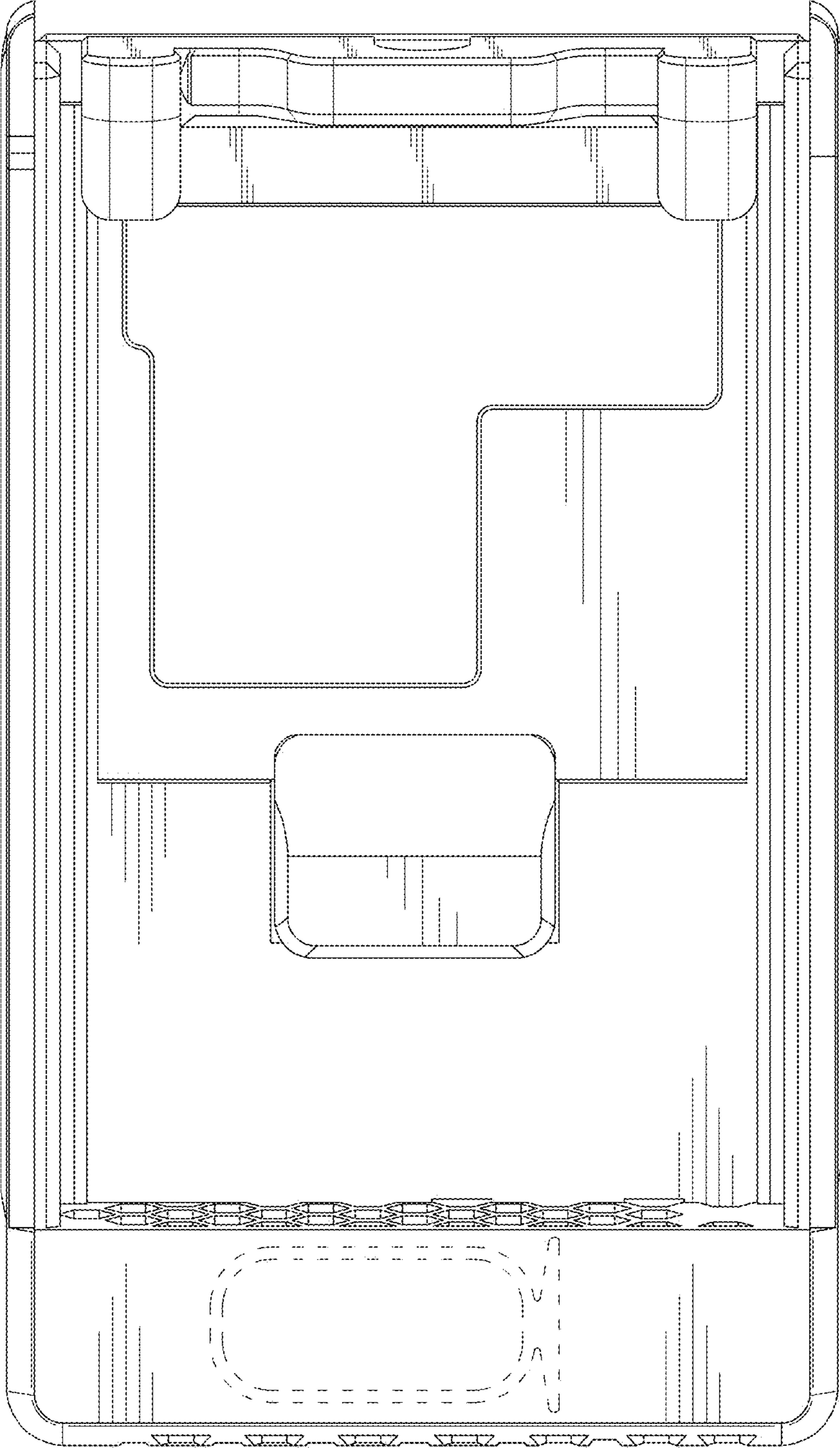


FIG. 6



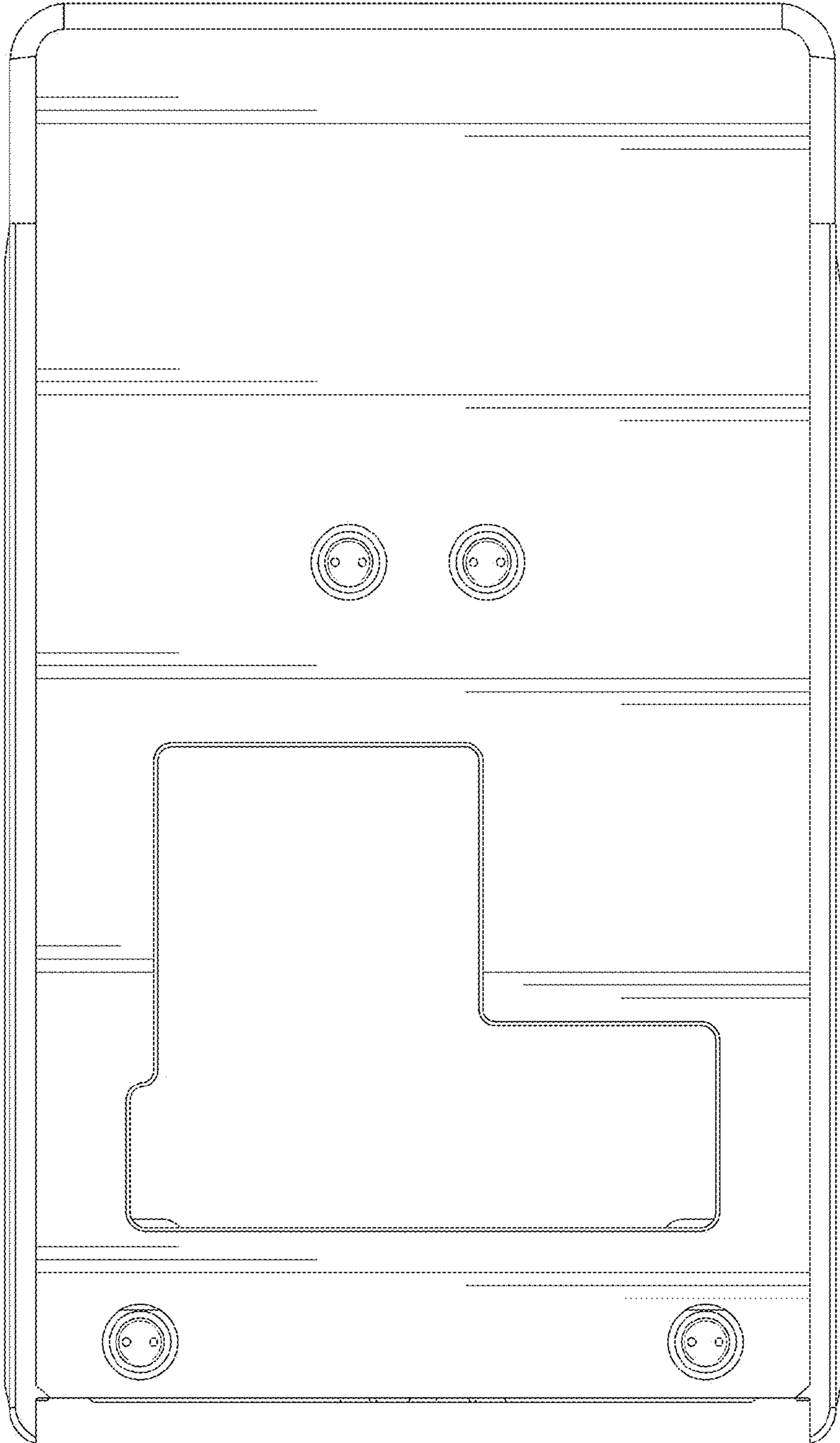


FIG. 7

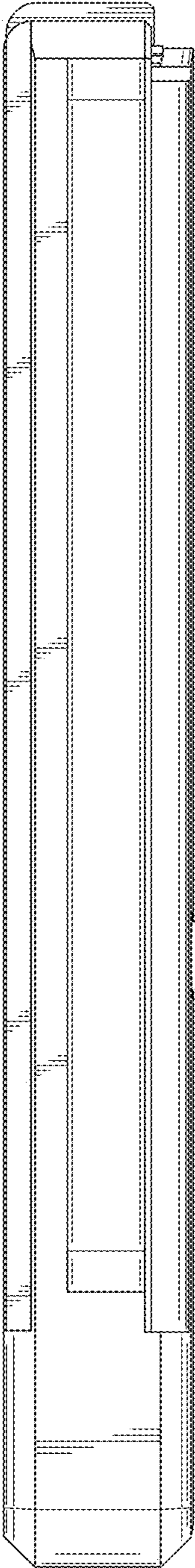


FIG. 8

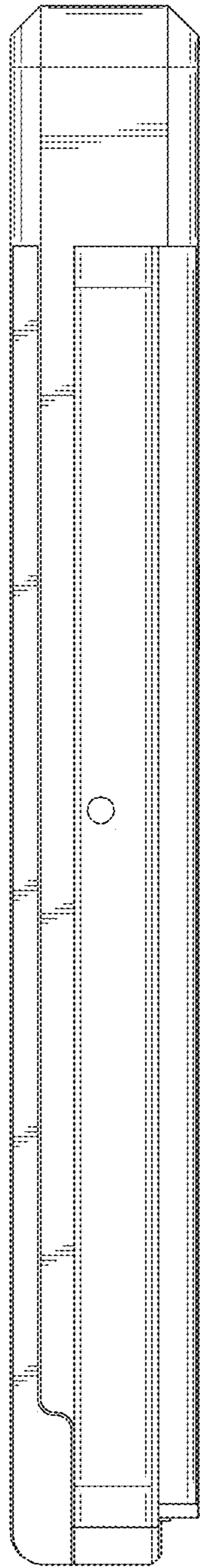


FIG. 9